G3

b2

20

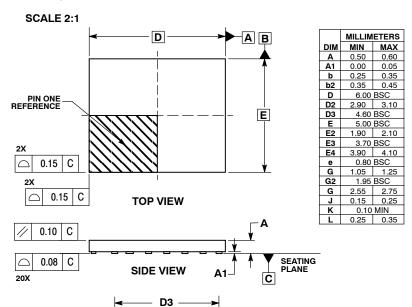
E4

20X

е



DATE 14 JAN 2014



G2

Ò

D2 **BOTTOM VIEW**

Ъ

П ф **e** 16X

E2 E3

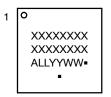
b Ф

19X

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994 . CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION & APPLIES TO PLATED
 TERMINAL AND IS MEASURED BETWEEN
- 0.25 AND 0.30 MM FROM TERMINAL. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code

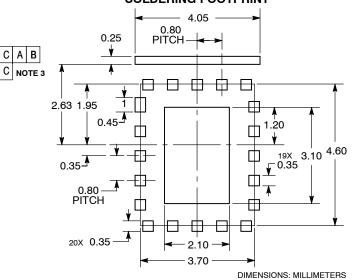
= Assembly Location

= Wafer Lot 11 = Year WW = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

SOLDERING FOOTPRINT



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DESCRIPTION:	20 PIN LLGA, 6X5X0.5, 0.8P		PAGE 1 OF 1

CAB

0.10

0.05

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